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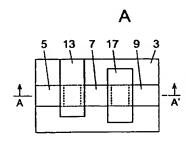
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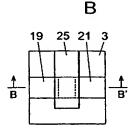
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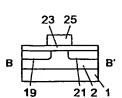
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(54) Title: SEMICONDUCTOR DEVICE

(57) Abstract: A semiconductor device is disclosed that includes a nonvolatile memory gate oxide film that is arranged on a semiconductor substrate, and a floating gate made of polysilicon that is arranged on the semiconductor substrate, and a selection gate oxide film. The recipheral circuit transistor includes a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit transistor includes a selection gate oxide film. The peripheral circuit transistor includes a peripheral circuit transistor includes a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit transistor includes a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit transistor. includes a peripheral circuit gate oxide film that is arranged on the semiconductor substrate, and a peripheral circuit gate made of polysilicon that is arranged on the peripheral circuit gate oxide film. The memory gate oxide film is arranged to be thinner than the peripheral circuit gate oxide film.



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